

July 2015

MOC3010M, MOC3011M, MOC3012M, MOC3020M, MOC3021M, MOC3022M, MOC3023M 6-Pin DIP Random-Phase Triac Driver Output Optocoupler (250/400 Volt Peak)

Features

- Excellent I_{FT} Stability—IR Emitting Diode Has Low Degradation
- · Peak Blocking Voltage
 - 250 V, MOC301XM
 - 400 V, MOC302XM
- Safety and Regulatory Approvals
 - UL1577, 4,170 VAC_{RMS} for 1 Minute
 - DIN EN/IEC60747-5-5

Applications

- Industrial Controls
- Solenoid/Valve Controls
- · Traffic Lights
- · Static AC Power Switch
- · Vending Machines
- · Incandescent Lamp Dimmers
- · Solid State Relay
- Motor Control
- Lamp Ballasts

Description

The MOC301XM and MOC302XM series are optically isolated triac driver devices. These devices contain a GaAs infrared emitting diode and a light activated silicon bilateral switch, which functions like a triac. They are designed for interfacing between electronic controls and power triacs to control resistive and inductive loads for 115 V_{AC} operations.

Schematic Package Outlines ANODE 1 ANODE 2 *DO NOT CONNECT (TRIAC SUBSTRATE) Figure 1. Schematic Package Outlines Figure 2. Package Outlines

Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter	Characteristics	
Installation Classifications per DIN VDE	< 150 V _{RMS}	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V _{RMS}	I–IV
Climatic Classification		40/85/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V	Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test with $t_m = 10$ s, Partial Discharge < 5 pC	1275	V _{peak}
V _{PR}	Input-to-Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m = 1$ s, Partial Discharge < 5 pC	1594	V _{peak}
V _{IORM}	Maximum Working Insulation Voltage	850	V _{peak}
V _{IOTM}	Highest Allowable Over-Voltage	6000	V _{peak}
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
R _{IO}	Insulation Resistance at T _S , V _{IO} = 500 V	> 10 ⁹	Ω

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A = 25^{\circ}$ C unless otherwise specified.

Symbol	Parameters	Device	Value	Unit
TOTAL DE	/ICE			1
T _{STG}	Storage Temperature	All	-40 to +150	°C
T _{OPR}	Operating Temperature	All	-40 to +85	°C
TJ	Junction Temperature Range	All	-40 to +100	°C
T _{SOL}	Lead Solder Temperature	All	260 for 10 seconds	°C
0	Total Device Power Dissipation at 25°C Ambient	All	330	mW
P_{D}	Derate Above 25°C	All	4.4	mW/°C
EMITTER				
I _F	Continuous Forward Current	All	60	mA
V _R	Reverse Voltage	All	3	V
Р	Total Power Dissipation at 25°C Ambient	All	100	mW
P_{D}	Derate Above 25°C	All	1.33	mW/°C
DETECTOR	i i			
		MOC3010M MOC3011M MOC3012M	250	
V _{DRM}	Off-State Output Terminal Voltage	MOC3020M MOC3021M MOC3022M MOC3023M	400	V
I _{TSM}	Peak Repetitive Surge Current (PW = 100 μs, 120 pps)	All	1	Α
D	Total Power Dissipation at 25°C Ambient	All	300	mW
P_{D}	Derate Above 25°C	All	4	mW/°C

Electrical Characteristics

 $T_A = 25$ °C unless otherwise specified.

Individual Component Characteristics

Symbol	Parameters	Test Conditions	Device	Min.	Тур.	Max.	Unit
EMITTER				•	•		
V _F	Input Forward Voltage	I _F = 10 mA	All		1.15	1.50	V
I _R	Reverse Leakage Current V _R = 3 V, T _A = 25°C		All		0.01	100	μΑ
DETECTO	DETECTOR						
I _{DRM}	Peak Blocking Current, Either Direction	Rated V_{DRM} , $I_F = 0^{(1)}$	All		10	100	nA
V _{TM}	Peak On-State Voltage, Either Direction	$I_{TM} = 100 \text{ mA peak}, I_F = 0$	All		1.8	3.0	V

Transfer Characteristics

Symbol	DC Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
			MOC3020M			30	
			MOC3010M		15		
			MOC3021M			13	
I _{FT}	I _{FT} LED Trigger Current	Voltage = 3 V ⁽²⁾	MOC3011M			10	mA
			MOC3022M			10	
			MOC3012M			_	
			MOC3023M			5	
I _H	Holding Current, Either Direction		All		100		μΑ

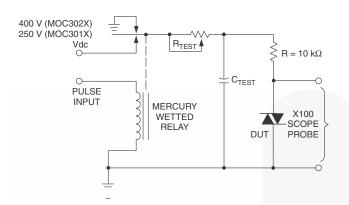
Isolation Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Тур.	Max.	Unit
V_{ISO}	Isolation Voltage ⁽³⁾	t = 1 Minute	All	4170			VAC _{RMS}

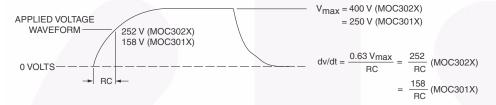
Notes:

- 1. Test voltage must be applied within dv/dt rating.
- 2. All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT} . Therefore, recommended operating I_F lies between max I_{FT} (30 mA for MOC3020M, 15 mA for MOC3010M and MOC3021M, 10 mA for MOC3011M and MOC3022M, 5 mA for MOC3012M and MOC3023M) and absolute maximum I_F (60 mA).
- 3. Isolation voltage, V_{ISO} , is an internal device dielectric breakdown rating. For this test, pins 1 and 2 are common, and pins 4, 5 and 6 are common.

Typical Performance Curves 800 1.7 600 FORWARD VOLTAGE (V) (mA) 400 ON-STATE CURRENT 1.5 200 1.3 -200 -400 1.1 -600 -800 100 -3 0 I_F - LED FORWARD CURRENT (mA) V_{TM} - ON-STATE VOLTAGE (V) Figure 4. On-State Characteristics Figure 3. LED Forward Voltage vs. Forward Current TRIGGER CURRENT (NORMALIZED) I_{TM} - TRIGGER CURRENT (NORMALIZED) NORMALIZED TO: 20 1.2 1.0 0.9 0.7 NORMALIZED TO TA = 25°C PW_{in} - LED TRIGGER WIDTH (µs) 0.6 40 100 Figure 6. LED Current Required to Trigger vs. LED Pulse Width AMBIENT TEMPERATURE - T_A (°C) Figure 5. Trigger Current vs. Ambient Temperature 10000 STATIC dv/dt I_{DRM} - LEAKAGE CURRENT (nA) 1000 STATIC dv/dt (V/µs) 100 10 25 30 100 T_A - AMBIENT TEMPERATURE (°C) Figure 7. dv/dt vs. Temperature -40 100 T_A - AMBIENT TEMPERATURE (°C) Figure 8. Leakage Current, I_{DRM} vs. Temperature



- The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
- 100x scope probes are used, to allow high speeds and voltages.
- 3. The worst-case condition for static dv/dt is established by triggering the DUT with a normal LED input current, then removing the current. The variable R_{TEST} allows the dv/dt to be gradually increased until the DUT continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the DUT stops triggering. τ_{RC} is measured at this point and recorded.



Note:

This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

Figure 9. Static dv/dt Test Circuit

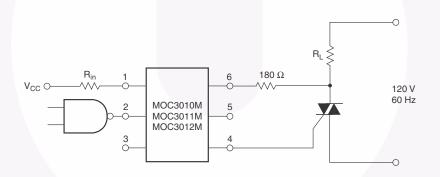


Figure 10. Resistive Load

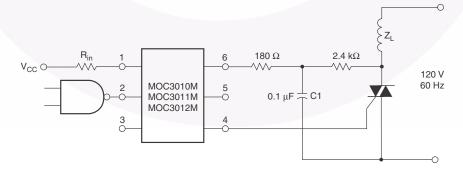


Figure 11. Inductive Load with Sensitive Gate Triac ($I_{GT} \le 15 \text{ mA}$)

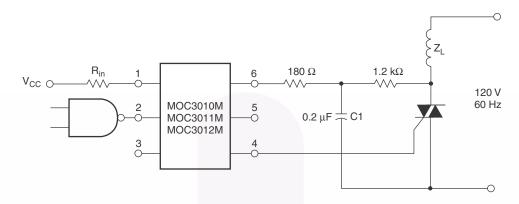
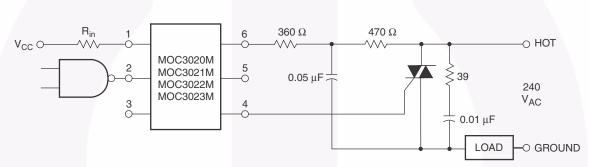


Figure 12. Inductive Load with sensitive Gate Triac ($I_{GT} \le 15 \text{ mA}$)



In this circuit the "hot" side of the line is switched and the load connected to the cold or ground side.

The 39 Ω resistor and 0.01 μ F capacitor are for snubbing of the triac, and the 470 Ω resistor and 0.05 μ F capacitor are for snubbing the coupler. These components may or may not be necessary depending upon the particular and load used.

Figure 13. Typical Application Circuit

Reflow Profile

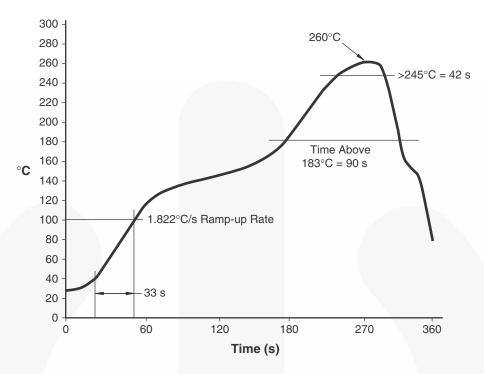


Figure 14. Reflow Profile

Ordering Information(4)

Part Number	Package	Packing Method
MOC3010M	DIP 6-Pin	Tube (50 Units)
MOC3010SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
MOC3010SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
MOC3010VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MOC3010SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
MOC3010SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
MOC3010TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

Note:

4. The product orderable part number system listed in this table also applies to the MOC3011M, MOC3012M, MOC3020M, MOC3021M, MOC3022M, and MOC3023M product families.

Marking Information

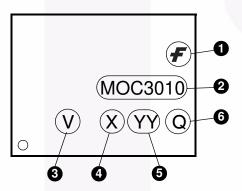
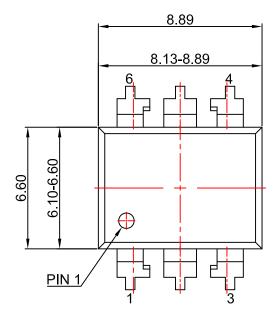
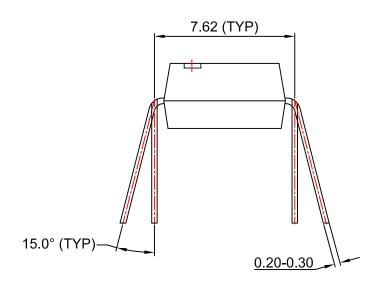
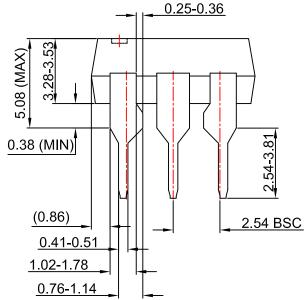


Figure 15. Top Mark

Тор Ма	Top Mark Definitions					
1	Fairchild Logo					
2	Device Number					
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)					
4	One-Digit Year Code, e.g., '5'					
5	Two-Digit Work Week, Ranging from '01' to '53'					
6	Assembly Package Code					



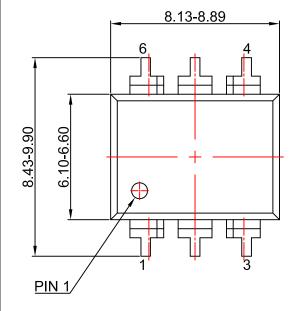


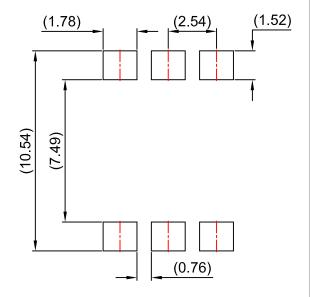


NOTES:

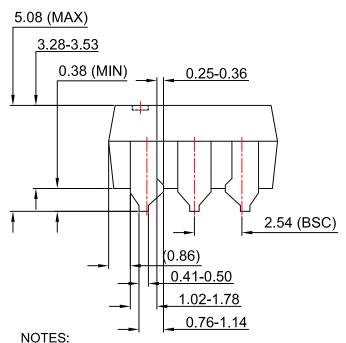
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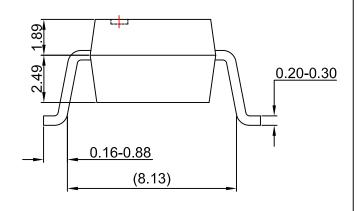






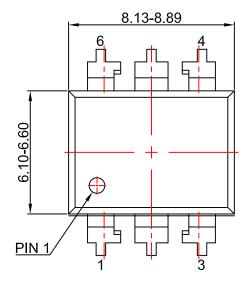
LAND PATTERN RECOMMENDATION

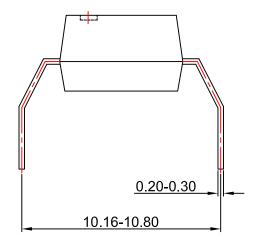


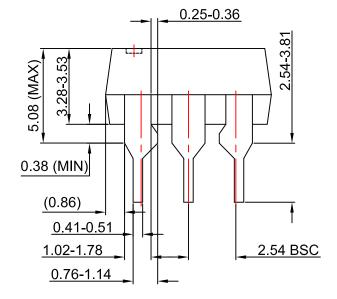


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Definition of Terms

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Datasheet Identification		Definition
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